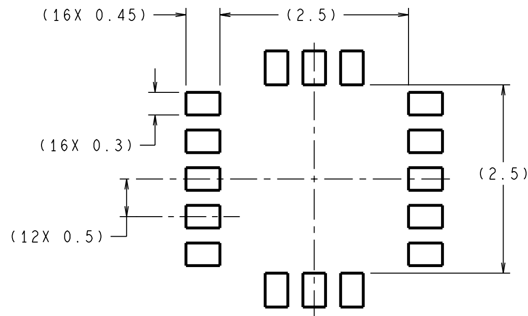
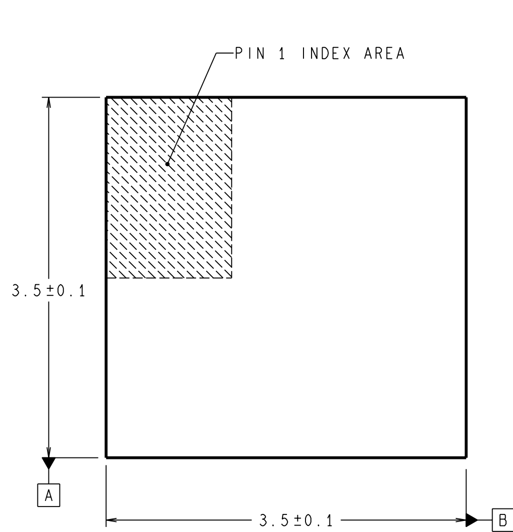
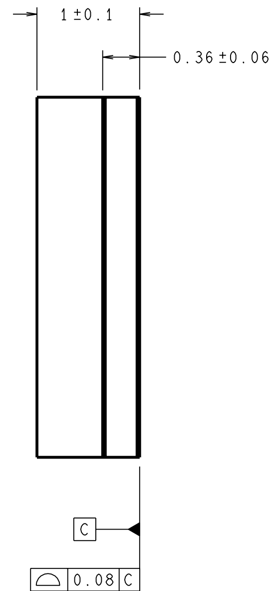
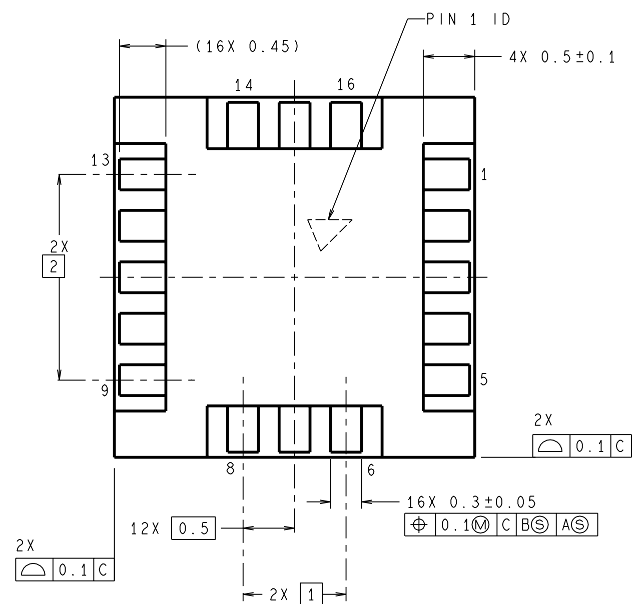
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12027	06/18/1998	TL/AP
B	UPDATE BOT METAL & MASK LAYERS PER P/P DWG; REV NOTES 2 & 3; REV GEOMETRIC TOL	12094	09/24/1998	TL/



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS







DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS
   Ni 10 ± 5 MICROMETERS
   Au 1 ± 0.5 MICROMETER
3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION CCE, DATED SEPTEMBER 1998.

APPROVALS	DATE	National Semiconductor 2900 Semiconductor dr, Santa Clara, CA 95052-8090
DRAWN T. LEQUANG	06/18/1998	
DFTG. CHK.		CSP, PLASTIC, LAMINATED, 3.5 X 3.5 X 1.0 mm BODY, 16 L, 0.5 mm PITCH
ENGR. CHK.		

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	(SC)MKT-SLB16A	B
	DO NOT SCALE DRAWING		SHEET 1 of 1	